

As a below-named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR CHIP ASSEMBLIES, METHODS OF MAKING SAME AND COMPONENTS FOR SAME
the specification of which

☐ is attached hereto

☒ was filed on October 7, 1994 as United States Application Number 08/319,966.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, § 119(a)-(d) of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before the application on which priority is claimed:

PRIOR FOREIGN APPLICATION(S)			
COUNTRY	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY CLAIMED
NONE			YES <input type="checkbox"/> NO <input type="checkbox"/>

LISTING OF FOREIGN APPLICATIONS CONTINUED ON PAGE 2 HEREOF ☐ YES ☒ NO

I hereby claim the benefit under Title 35, United States Code, § 119(e) of any United States provisional application(s) listed below:

NONE

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

Application Serial Number: 08/030,194	Filing Date: April 28, 1993	Status (patented, pending, abandoned): Pending
Application Serial Number: 07/765,928	Filing Date: September 24, 1991	Status (patented, pending, abandoned): Patented
Application Serial Number: 07/673,020	Filing Date: March 21, 1991	Status (patented, pending, abandoned): Patented
Application Serial Number: 07/586,758	Filing Date: September 24, 1990	Status (patented, pending, abandoned): Patented

LISTING OF US APPLICATIONS CONTINUED ON PAGE 2 HEREOF: NO

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith.

Lawrence I. Lerner, Reg. No. 18,516; Sidney David, Reg. No. 22,768; Joseph E. Littenberg, Reg. No. 20,832; Arnold H. Krumholz, Reg. No. 25,428; William L. Mentlik, Reg. No. 27,108; John R. Nelson, Reg. No. 28,573; Roy H. Wegner, Reg. No. 28,350; Stephen B. Goldman, Reg. No. 28,512; Paul H. Kochanski, Reg. No. 29,860; Marcus J. Millet, Reg. No. 28,241; Bruce H. Sales, Reg. No. 32,793; Daniel H. Bohns, Reg. No. 18,694; Peter J. Butch III, Reg. No. 32,203; Keith E. Garman, Reg. No. 32,137; Robert B. Cohen, Reg. No. 32,768; Arnold B. Dompier, Reg. No. 29,736; Michael H. Teaschner, Reg. No. 32,852; Jeffrey S. Dickey, Reg. No. 35,858; Gregory S. Gewirtz, Reg. No. 36,522; Jonathan A. David, Reg. No. 36,494; Shawn P. Foley, Reg. No. 33,071; Lawrence G. Fridman, Reg. No. 31,815; Christopher M. Pickett, Reg. No. 37,531.

SEND CORRESPONDENCE TO:
LERNER, DAVID, LITTENBERG,
KRUMHOLZ & MENTLIK
600 South Avenue West
Westfield, New Jersey 07090

DIRECT TELEPHONE CALLS TO:
(name and telephone number)

MARCUS J. MILLET
(908) 654-5000

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor (given name, family name): IGOR Y. KHANDROS

Inventor's signature _____ Date _____

Residence: ORINDA, CALIFORNIA Citizenship: U.S.A.
Post Office Address: 25 HACIENDAS ROAD, ORINDA, CALIFORNIA, 94563

Full name of second joint inventor, if any (given name, family name) THOMAS H. DISTEFANO

Second Inventor's signature Thomas H. Distefano Date OCTOBER 9, 1996

Residence: MONTE SERENO, CALIFORNIA Citizenship: U.S.A.
Post Office Address: 15363 ROBIN ANN LANE, MONTE SERENO, CA 95030

☐ NO Additional inventors are being named on separately numbered sheets attached hereto.

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NONE			YES <input type="checkbox"/> NO <input type="checkbox"/>
LISTING OF FOREIGN APPLICATIONS CONTINUED ON PAGE 2 HEREOF <input type="checkbox"/> YES <input checked="" type="checkbox"/> NO			

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NONE

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Application Serial Number: 08/030,194	Filing Date: April 28, 1993	Status (patented, pending, abandoned): Pending
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Full name of sole or first inventor (given name, family name): **IGOR Y. KHANDROS**

Inventor's signature

Date

11/15/96

Residence: **ORINDA, CALIFORNIA**

Citizenship: **U.S.A.**

Post Office Address: **25 HACIENDAS ROAD, ORINDA, CALIFORNIA, 94563**

Full name of second joint inventor, if any (given name, family name) **THOMAS H. DISTEFANO**

Second Inventor's signature

Date

Residence: **MONTE SERENO, CALIFORNIA**

Citizenship: **U.S.A.**

Post Office Address: **15363 ROBIN ANN LANE, MONTE SERENO, CA 95030**

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SEMICONDUCTOR CHIP ASSEMBLIES, METHODS OF MAKING SAME AND COMPONENTS FOR SAME

the specification of which

☐ is attached hereto☐ was filed on _____ as Application Serial No. _____ and was amended on _____ (if applicable)☒ was described and claimed in International Application No. PCT/US91/06920 filed 9/24/91 and as amended on _____ (if any)

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a)

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PRIOR FOREIGN APPLICATION(S)

COUNTRY	APPLICATION NUMBER	DATE OF FILING (day, month, year)	PRIORITY CLAIMED UNDER 35 U.S.C. 119
US	07/586,758	9/24/90	YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>
US	07/673,020	3/21/91	YES <input checked="" type="checkbox"/> NO <input type="checkbox"/>
			YES <input type="checkbox"/> NO <input type="checkbox"/>

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(Application Serial No.)	(Filing Date)	(Status) (patented, pending, abandoned)
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SEND CORRESPONDENCE TO:

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DIRECT TELEPHONE CALLS TO:

(name and telephone number)
Joseph S. Littenberg
(908) 654-5000

201	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME
		KHANDROS	Igor	Y.
	CITY	Peekskill	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP
	POST OFFICE ADDRESS	CITY	STATE OR COUNTRY	ZIP CODE
		503 Furnace Dock Road	Peekskill	New York 10566
202	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME
		DISTEFANO	Thomas	H.
	CITY	Bronxville	STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP
	POST OFFICE ADDRESS	CITY	STATE OR COUNTRY	ZIP CODE
		29 Birch Brook Road	Bronxville	New York 10708
203	FULL NAME OF INVENTOR	LAST NAME	FIRST NAME	MIDDLE NAME
	CITY		STATE OR FOREIGN COUNTRY	COUNTRY OF CITIZENSHIP
	POST OFFICE ADDRESS	CITY	STATE OR COUNTRY	ZIP CODE

LISTING OF INVENTORS CONTINUED ON PAGE 2 HEREOF. ☐ YES ☒ NO

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SIGNATURE OF INVENTOR 201	SIGNATURE OF INVENTOR 202	SIGNATURE OF INVENTOR 203
<i>[Signature]</i>	<i>[Signature]</i>	
DATE	DATE	DATE
3/3/93	3/16/93	

SEE PAGE 2 ATTACHED, SIGNED AND MADE A PART HEREOF: ☐ YES ☒ NO

*Where use of Page 2 of this Declaration is necessary, only Page 2 is signed.